

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		Yonehara-Takao.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:43
L1	6	("5597766" "5888882" "6017804"). PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 08:57
L5	1	'JP 411317509'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 09:30
L7	528	@ad<="20010131" and (438/113-114).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 09:40
L8	2105	@ad<="20010131" and (438/460-465).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 09:41
L9	2	("6677183").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 09:42
L10	202	@ad<="20010131" and 'IC' and 'separation' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:12
L11	94	@ad<="20010131" and 'die' same 'separation' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:08
L12	6	@ad<="20010131" and 'IC' with 'separation' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:13
L13	95	@ad<="20010131" and 'chip' with 'separation' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:30

L14	134	@ad<="20010131" and 'chip' same 'separation' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:18
L15	13	@ad<="20010131" and 'IC' same 'separation' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:29
L20	3	@ad<="20010131" and 'chip' same 'cleavage' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:29
L21	13	@ad<="20010131" and 'chip' same 'split' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:28
L22	4	@ad<="20010131" and 'IC' same 'dicing' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:28
L23	9	@ad<="20010131" and 'chip' same 'dicing' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:28
L24	144	@ad<="20010131" and 'chip' same 'dicing' with 'pressure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:28
L25	11	@ad<="20010131" and 'IC' same 'dicing' with 'pressure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:28
L26	38	@ad<="20010131" and 'chip' same 'split' with 'pressure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:28
L27	12	@ad<="20010131" and 'chip' same 'cleavage' with 'pressure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:29
L28	50	@ad<="20010131" and 'IC' same 'separation' with 'pressure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:29

L29	85	@ad<="20010131" and 'chip' with 'separation' with 'pressure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:30
S1	1	Kiyofumi-Sakaguchi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 08:57
S2	12780	Sakaguchi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 12:27
S3	151	Sakaguchi-Kiyofumi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:36
S4	2561	((257/620) or (438/460-465)). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 09:40
S5	1	"20020102758"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 12:55
S6	434	((((257/620) or (438/460-465)). CCLS.) and @ad<="20010131" and 'scribe'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 14:42
S7	31	@ad<="20010131" and 'dicing' and 'separation' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 10:06
S8	12	(((((257/620) or (438/460-465)). CCLS.) and @ad<="20010131" and 'scribe') and 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:38
S9	704	@ad<="20010131" and 'semiconductor' and 'kerf'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 14:59
S10	88	@ad<="20010131" and 'semiconductor' and 'kerf' and 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 10:07

S11	1	@ad<="20010131" and 'dicing' and 'separation' near 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 10:07
S12	318	@ad<="20010131" and (438/462). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 15:27
S13	14	@ad<="20010131" and (438/462). ccls. and fluid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 15:54
S14	181	@ad<="20010131" and (438/462). ccls. and 'separated'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 16:04
S15	70042	@ad<="20010131" and 'separation' with 'liquid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 16:17
S16	84	@ad<="20010131" and 'separation' with 'high pressure fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/17 16:11
S17	252108	((("438") or ("257"))).CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/10/17 16:19
S18	998	@ad<="20010131" and 'thin-film semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/18 08:17
S19	15	(@ad<="20010131" and 'thin-film semiconductor') and 'dicing'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/18 08:18
S20	136	'semiconductor' and 'die separation'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/18 08:26
S21	426	'wafer' and 'dicing method'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/18 09:10

S22	1	"5149586".PN.	USPAT	OR	OFF	2002/10/18 08:36
S23	1	"5281473".PN.	USPAT	OR	OFF	2002/10/18 08:36
S24	1	"5525422".PN.	USPAT	OR	OFF	2002/10/18 08:37
S25	1	"6176966".PN.	USPAT	OR	OFF	2002/10/18 08:38
S26	6	'wafer' and 'dicing method' with 'pressure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/18 09:06
S27	85	Sakaguchi-Kiyofumi.in. and apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/18 10:22
S28	1	"20020100941"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/10/28 08:02
S29	896	@ad<="20010131" and 'scribe' and 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/03/07 09:31
S30	20	@ad<="20010131" and (438/464). ccls. and 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/03/07 09:55
S31	143	@ad<="20010131" and 'scribe' and 'fluid' and 'crack'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/03/07 09:31
S32	121	@ad<="20010131" and (438/464). ccls. and 'crack'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:39
S33	335	@ad<="20010131" and (438/460). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:55
S34	194	@ad<="20010131" and (438/461). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:55
S35	331	@ad<="20010131" and (438/462). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:56

S36	40	@ad<="20010131" and (438/463). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:56
S37	932	@ad<="20010131" and (438/464). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/03/07 11:58
S38	471	@ad<="20010131" and (438/465). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:56
S39	386	@ad<="20010131" and (257/620). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:56
S40	496	@ad<="20010131" and (438/113-114).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/17 13:45
S41	396	@ad<="20010131" and (257/620). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/17 13:41
S42	509	@ad<="20010131" and (438/113-114).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 09:40
S43	347	@ad<="20010131" and (438/460). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/17 13:42
S44	277	@ad<="20010131" and (438/458). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/17 13:43
S45	509	@ad<="20010131" and (438/113-114).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/17 13:46
S46	222	Sakaguchi-Kiyofumi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:44

S47	2	"20040082149"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:42
S48	33	Yonehara-Takao.in. and 'anodizing' and 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:44
S49	70	Sakaguchi-Kiyofumi.in. and 'anodizing' and 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:44
S50	62	Sakaguchi-Kiyofumi.in. and 'anodizing' and 'pressure' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:44
S51	490	@ad<="20010131" and 'semiconductor' and 'notch' and 'pressure' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 10:09
S52	8	@ad<="20010131" and 'separation' with 'semiconductor' and 'notch' and 'pressure' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/23 15:58
S53	1	'JP 11317509'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 10:23
S54	1	'JP11317509'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 10:22
S55	1	'11317509'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/23 15:29
S56	1	'JP11317509'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/23 15:30
S57	1	'JP11039261'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/23 15:30

S58	90	@ad<="20010131" and 'separation' with 'semiconductor' and 'open' and 'pressure' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/23 15:59
S59	2	@ad<="20010131" and 'separation' with 'semiconductor' and 'kerf' and 'pressure' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/23 15:59
S60	8	@ad<="20010131" and 'separation' with 'semiconductor' and 'notch' and 'pressure' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 14:07
S61	30	@ad<="20010131" and 'SOL' same 'separation' and 'pressure' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 14:08
S62	75	'SOL' same 'separation' and 'pressure' with 'fluid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 14:08
S63	950	@ad<="20010131" and (438/464). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:40
S64	359	@ad<="20010131" and (438/460). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:56
S65	196	@ad<="20010131" and (438/461). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:56
S66	361	@ad<="20010131" and (438/462). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:56
S67	42	@ad<="20010131" and (438/463). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:56
S68	479	@ad<="20010131" and (438/465). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:57

S69	404	@ad<="20010131" and (257/620). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 15:57
S70	524	@ad<="20010131" and (438/113-114).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 09:41
S71	122	@ad<="20010131" and (438/311). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 16:01
S72	711	@ad<="20010131" and (438/479). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 16:02
S73	55	@ad<="20010131" and (438/480). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 16:02
S74	180	@ad<="20010131" and (438/481). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 16:03
S75	202	@ad<="20010131" and (438/910). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/04 16:03